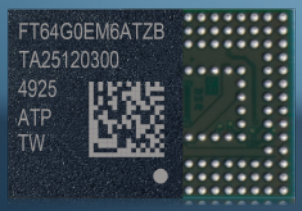
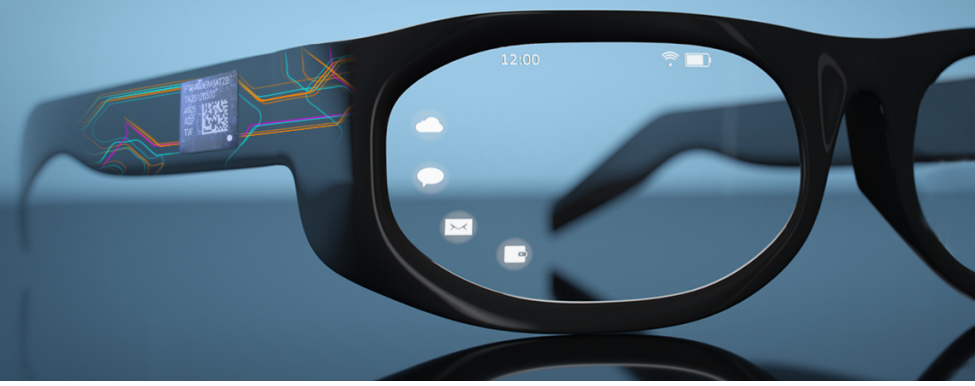
DISCOVER THE WORLD'S SMALLEST e.MMC AT 6.7 mm TO POWER NEXT-GEN SMART WEARABLES





ATP's 6.7 mm e.MMC redefines the storage standard for smart glasses and wearable devices. This innovation not only shrinks device size, but also slashes power consumption, paving the way for sleek, lightweight AR and XR glasses. With broad system-on-a-chip (SoC) compatibility and flexible development options, ATP e.MMC empowers designers to accelerate innovation and speed up market entry.

Perfect fit for AR/VR/XR, next-gen wearables, and more

- Features a 125-ball design while maintaining JEDEC compatibility
- Ultra-thin 0.65 mm z-height design profile in consideration of smart glasses with slim, rectangular frames
- Seamless pairing with discrete LPDDR and major SoC platforms
- Other small-footprint e.MMC offerings available: 9 x 10, 7.2 x 7.2
- Flexible sample ordering system speeds up prototyping and research and development (R&D)

Up to 70% power savings

Extended wearable usage with ATP's Auto Power-Saving Mode and Power Optimization technologies

67% smaller

than standard e.MMC packages, ideal for space-constrained applications

64 GB Native TLC 20 GB pSLC mode

Optimal for mainstream low- and mid-end positioning wearable devices

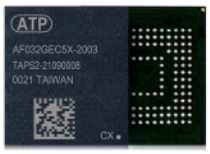
Enhanced Data Integrity

Advanced error correction, wear leveling, and Auto/Dynamic Data Refresh for superior data protection against read disturb and other retention issues

6.7 x 7.2 x 0.65 mm e.MMC

7.2 x 7.2 x 0.8 mm e.MMC

9.0 x 10.0 x 0.8 mm e.MMC



Product Line	Smaller Footprint e.MMC					
	Premium	Value	Premium	Value		
	E700Pc	E600Vc	E700Pc	E600Vc	E600Vi	E600Vc
Flash Type	3D TLC (pSLC mode)	3D TLC	3D TLC (pSLC mode)	3D TLC		
IC Package	125-ball FBGA		153-ball FBGA			
JEDEC Specification	v5.1, HS400					
Power Loss Protection Options	Firmware Based					
Operating Temperature	-25°C to 85°C				-40°C to 85°C	-25°C to 85°C
Capacity	20 GB	64 GB	20 GB to 40 GB	64 GB to 128 GB	32 GB to 64 GB	
Performance						
Sequential Read/ Write up to (MB/s) (Max.)	240 / 210		240 / 220		290 / 225	
Bus Speed Modes	x1 / x4 / x8					
ICC (Typical RMS in Read/Write) mA (Max.)	30 / 40		35 / 45		100 / 110	
ICCQ (Typical RMS in Read/Write) mA (Max.)	60 / 50		60 / 55		105 / 100	
Endurance and Reliability						
Endurance TBW (Max.) [1]	680 TB	12 TB	1,360 TB	24 TB	55 TB	
Reliability MTBF @ 25°C	>3,000,000 hours				>2,000,000 hours	
Others						
Dimensions (mm)	6.7 x 7.2 x 0.65		7.2 x 7.2 x 0.8		9.0 x 10.0 x 0.8	
Certifications	RoHS, REACH					
Warranty	One Year					

1 All performance is collected or measured using ATP proprietary test environment, without file system overhead.

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Product spec and its related information are subject to change without advance notice.
Please refer to www.atpinc.com for latest information

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